

## Title (en)

Electroplating method using combination of vibrational flow in plating bath and plating current of pulse

## Title (de)

Elektroplattierverfahren mit einer Kombination von schwingender Bewegung im Abscheidungsbad und gepulstem Plattierungsstrom

## Title (fr)

Methode d'electrodeposition utilisant une combinaison de flux vibrationnel dans le bain de deposition et de courant pulsé de deposition

## Publication

**EP 1164208 A3 20031008 (EN)**

## Application

**EP 01112689 A 20010525**

## Priority

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- JP 2000243249 A 20000810
- JP 2001129994 A 20010426

## Abstract (en)

[origin: EP1164208A2] In an electroplating method, a plating target article (X) disposed so as to be in contact with plating bath (14) is set as a cathode while a metal member disposed so as to be in contact with the plating bath (14) is set as an anode, and a voltage is applied between the cathode and the anode while vibrational flow is induced by vibrating vibrational vanes (16f) which are fixed in multi-stage style to a vibrating rod (16e) vibrating in the plating bath (14) interlockingly with vibration generating means (16d). Plating current flowing from the anode through the plating bath (14) to the cathode is pulsed and alternately set to one of a first state where the plating current keeps a first value I1 for a first time T1 and a second state where the plating current keeps a second value I2 having the same polarity as the first value I1 for a second time T2, the first value I1 being five or more times larger than the second value I2, and the first time T1 being three or more times longer than the second time T2.

<IMAGE>

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## Citation (search report)

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- [AD] PATENT ABSTRACTS OF JAPAN vol. 1995, no. 02 31 March 1995 (1995-03-31)
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